

IRF7403PBF Datasheet



| | |
|------------------------------|---|
| DiGi Electronics Part Number | IRF7403PBF-DG |
| Manufacturer | Infineon Technologies |
| Manufacturer Product Number | IRF7403PBF |
| Description | MOSFET N-CH 30V 8.5A 8SO |
| Detailed Description | N-Channel 30 V 8.5A (Ta) 2.5W (Ta) Surface Mount 8-SO |

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Purchase and inquiry

Manufacturer Product Number:

IRF7403PBF

Series:

HEXFET®

FET Type:

N-Channel

Drain to Source Voltage (Vdss):

30 V

Drive Voltage (Max Rds On, Min Rds On):

4.5V, 10V

Vgs(th) (Max) @ Id:

1V @ 250µA

Vgs (Max):

±20V

FET Feature:

-

Operating Temperature:

-55°C ~ 150°C (Tj)

Supplier Device Package:

8-SO

Manufacturer:

Infineon Technologies

Product Status:

Discontinued at Digi-Key

Technology:

MOSFET (Metal Oxide)

Current - Continuous Drain (Id) @ 25°C:

8.5A (Ta)

Rds On (Max) @ Id, Vgs:

22mOhm @ 4A, 10V

Gate Charge (Qg) (Max) @ Vgs:

57 nC @ 10 V

Input Capacitance (Ciss) (Max) @ Vds:

1200 pF @ 25 V

Power Dissipation (Max):

2.5W (Ta)

Mounting Type:

Surface Mount

Package / Case:

8-SOIC (0.154", 3.90mm Width)

Environmental & Export classification

RoHS Status:

ROHS3 Compliant

REACH Status:

REACH Unaffected

HTSUS:

8541.29.0095

Moisture Sensitivity Level (MSL):

1 (Unlimited)

ECCN:

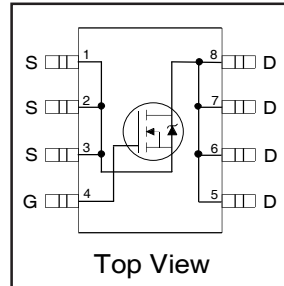
EAR99

International
IR Rectifier
 HEXFET® Power MOSFET

PD - 95301

IRF7403PbF

- Generation V Technology
- Ultra Low On-Resistance
- N-Channel Mosfet
- Surface Mount
- Available in Tape & Reel
- Dynamic dv/dt Rating
- Fast Switching
- Lead-Free



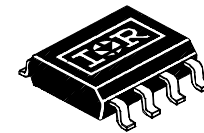
$$V_{DS} = 30V$$

$$R_{DS(on)} = 0.022\Omega$$

Description

Fifth Generation HEXFETs from International Rectifier utilize advanced processing techniques to achieve the lowest possible on-resistance per silicon area. This benefit, combined with the fast switching speed and ruggedized device design that HEXFET Power MOSFETs are well known for, provides the designer with an extremely efficient device for use in a wide variety of applications.

The SO-8 has been modified through a customized leadframe for enhanced thermal characteristics and multiple-die capability making it ideal in a variety of power applications. With these improvements, multiple devices can be used in an application with dramatically reduced board space. The package is designed for vapor phase, infra red, or wave soldering techniques. Power dissipation of greater than 0.8W is possible in a typical PCB mount application.



SO-8

Absolute Maximum Ratings

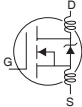
| | Parameter | Max. | Units |
|--------------------------|--|--------------|-------|
| $I_D @ T_A = 25^\circ C$ | 10 Sec. Pulsed Drain Current, $V_{GS} @ 10V$ | 9.7 | A |
| $I_D @ T_A = 25^\circ C$ | Continuous Drain Current, $V_{GS} @ 10V$ | 8.5 | |
| $I_D @ T_A = 70^\circ C$ | Continuous Drain Current, $V_{GS} @ 10V$ | 5.4 | |
| I_{DM} | Pulsed Drain Current ① | 34 | |
| $P_D @ T_A = 25^\circ C$ | Power Dissipation | 2.5 | W |
| | Linear Derating Factor | 0.02 | W/°C |
| V_{GS} | Gate-to-Source Voltage | ± 20 | V |
| dv/dt | Peak Diode Recovery dv/dt ② | 5.0 | V/ns |
| T_J, T_{STG} | Junction and Storage Temperature Range | -55 to + 150 | °C |

Thermal Resistance Ratings

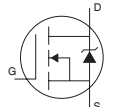
| | Parameter | Typ. | Max. | Units |
|-----------------|------------------------------|------|------|-------|
| $R_{\theta JA}$ | Maximum Junction-to-Ambient③ | — | 50 | °C/W |

IRF7403PbF

International
IOR RectifierElectrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

| | Parameter | Min. | Typ. | Max. | Units | Conditions |
|---------------------------------|--------------------------------------|------|-------|-------|---------------------|---|
| $V_{(BR)DSS}$ | Drain-to-Source Breakdown Voltage | 30 | — | — | V | $V_{GS} = 0V, I_D = 250\mu A$ |
| $\Delta V_{(BR)DSS}/\Delta T_J$ | Breakdown Voltage Temp. Coefficient | — | 0.024 | — | V/ $^\circ\text{C}$ | Reference to $25^\circ\text{C}, I_D = 1\text{mA}$ |
| $R_{DS(ON)}$ | Static Drain-to-Source On-Resistance | — | — | 0.022 | Ω | $V_{GS} = 10V, I_D = 4.0A$ ③ |
| | | — | — | 0.035 | | $V_{GS} = 4.5V, I_D = 3.4A$ ③ |
| $V_{GS(th)}$ | Gate Threshold Voltage | 1.0 | — | — | V | $V_{DS} = V_{GS}, I_D = 250\mu A$ |
| g_{fs} | Forward Transconductance | 8.4 | — | — | S | $V_{DS} = 15V, I_D = 4.0A$ |
| I_{DSS} | Drain-to-Source Leakage Current | — | — | 1.0 | μA | $V_{DS} = 24V, V_{GS} = 0V$ |
| | | — | — | 25 | | $V_{DS} = 24V, V_{GS} = 0V, T_J = 125^\circ\text{C}$ |
| I_{GSS} | Gate-to-Source Forward Leakage | — | — | 100 | nA | $V_{GS} = 20V$ |
| | Gate-to-Source Reverse Leakage | — | — | -100 | | $V_{GS} = -20V$ |
| Q_g | Total Gate Charge | — | — | 57 | nC | $I_D = 4.0A$ |
| Q_{gs} | Gate-to-Source Charge | — | — | 6.8 | | $V_{DS} = 24V$ |
| Q_{gd} | Gate-to-Drain ("Miller") Charge | — | — | 18 | | $V_{GS} = 10V$, See Fig. 6 and 12 ③ |
| $t_{d(on)}$ | Turn-On Delay Time | — | 10 | — | ns | $V_{DD} = 15V$ |
| t_r | Rise Time | — | 37 | — | | $I_D = 4.0A$ |
| $t_{d(off)}$ | Turn-Off Delay Time | — | 42 | — | | $R_G = 6.0\Omega$ |
| t_f | Fall Time | — | 40 | — | | $R_D = 3.7\Omega$, See Fig. 10 ③ |
| L_D | Internal Drain Inductance | — | 2.5 | — | nH | Between lead tip and center of die contact  |
| L_S | Internal Source Inductance | — | 4.0 | — | | |
| C_{iss} | Input Capacitance | — | 1200 | — | pF | $V_{GS} = 0V$ |
| C_{oss} | Output Capacitance | — | 450 | — | | $V_{DS} = 25V$ |
| C_{rss} | Reverse Transfer Capacitance | — | 160 | — | | $f = 1.0\text{MHz}$, See Fig. 5 |

Source-Drain Ratings and Characteristics

| | Parameter | Min. | Typ. | Max. | Units | Conditions |
|----------|--|---|------|------|-------|--|
| I_S | Continuous Source Current (Body Diode) | — | — | 3.1 | A | MOSFET symbol showing the integral reverse p-n junction diode.  |
| I_{SM} | Pulsed Source Current (Body Diode) ① | — | — | 34 | | |
| V_{SD} | Diode Forward Voltage | — | — | 1.0 | V | $T_J = 25^\circ\text{C}, I_S = 2.0A, V_{GS} = 0V$ ③ |
| t_{rr} | Reverse Recovery Time | — | 52 | 78 | ns | $T_J = 25^\circ\text{C}, I_F = 4.0A$ |
| Q_{rr} | Reverse Recovery Charge | — | 93 | 140 | nC | $di/dt = 100A/\mu s$ ③ |
| t_{on} | Forward Turn-On Time | Intrinsic turn-on time is negligible (turn-on is dominated by L_S+L_D) | | | | |

Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature. (See fig. 11)
- ② $I_{SD} \leq 4.0A, di/dt \leq 180A/\mu s, V_{DD} \leq V_{(BR)DSS}, T_J \leq 150^\circ\text{C}$
- ③ Pulse width $\leq 300\mu s$; duty cycle $\leq 2\%$.
- ④ Surface mounted on FR-4 board, $t \leq 10\text{sec}$.

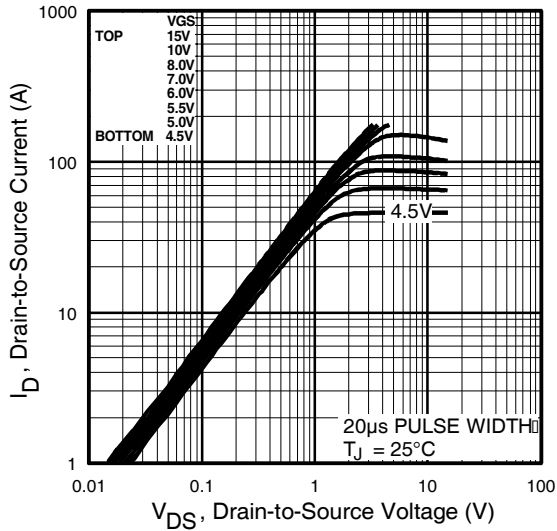


Fig 1. Typical Output Characteristics

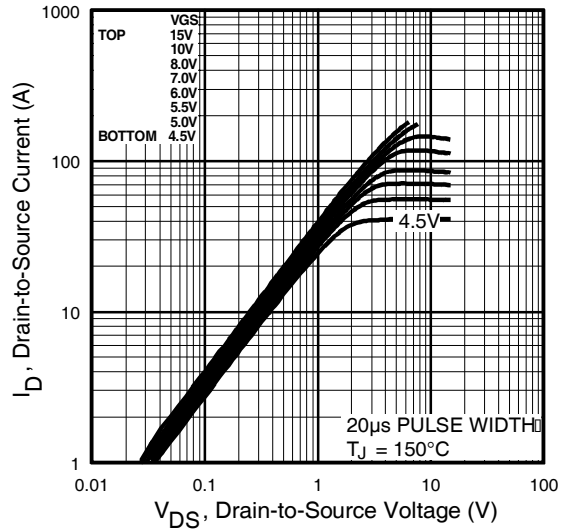


Fig 2. Typical Output Characteristics

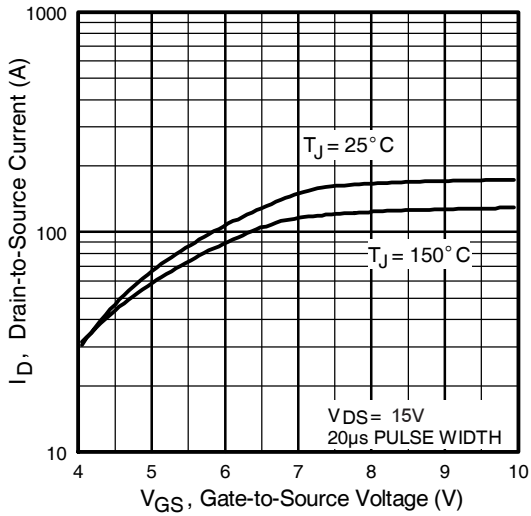


Fig 3. Typical Transfer Characteristics

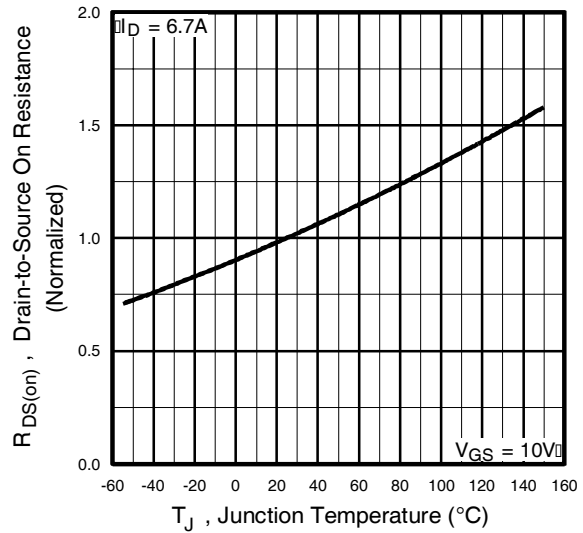


Fig 4. Normalized On-Resistance Vs. Temperature

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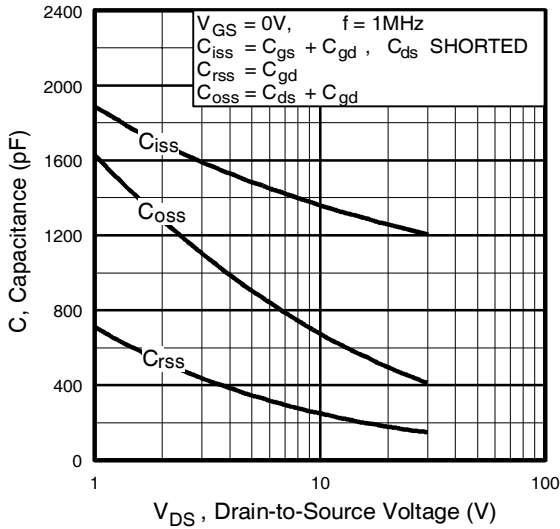


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

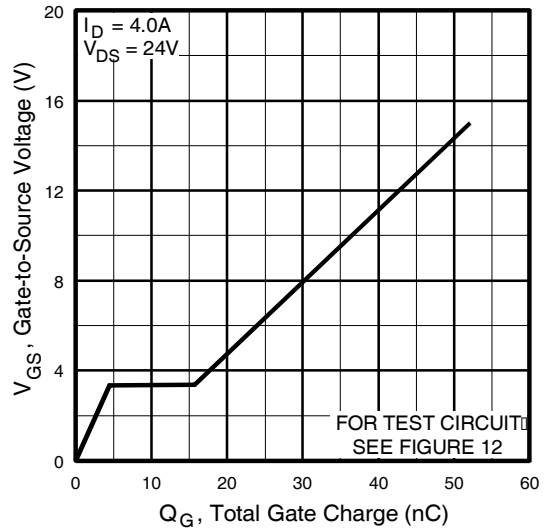


Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage

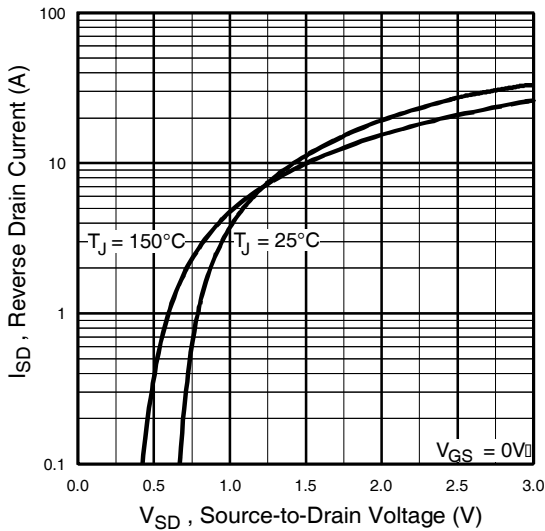


Fig 7. Typical Source-Drain Diode Forward Voltage

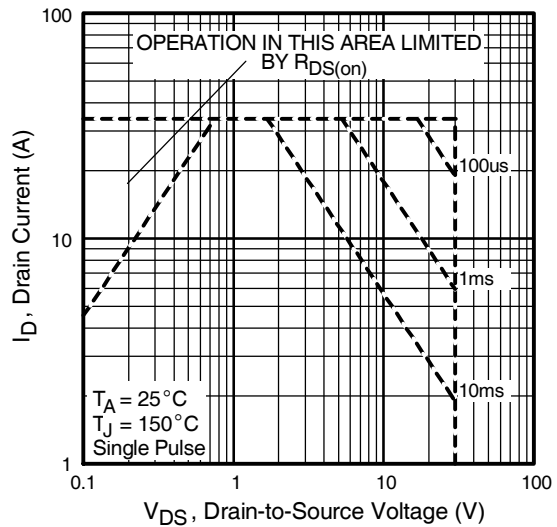


Fig 8. Maximum Safe Operating Area

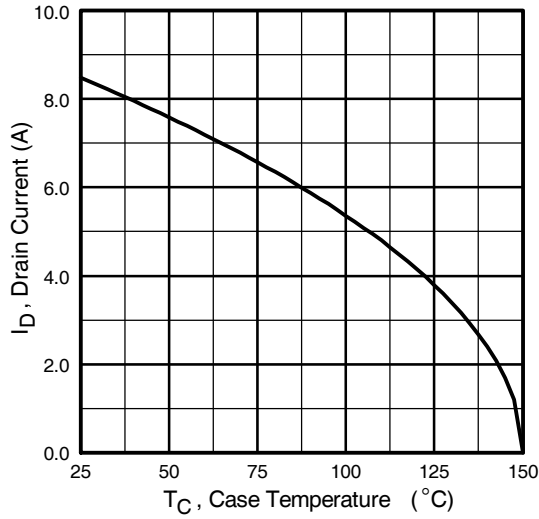


Fig 9. Maximum Drain Current Vs. Ambient Temperature

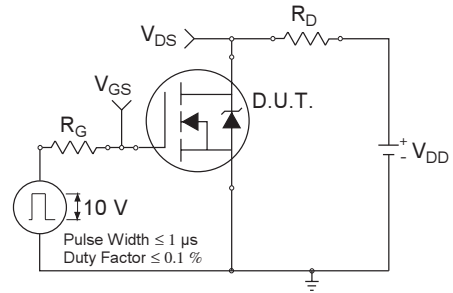


Fig 10a. Switching Time Test Circuit

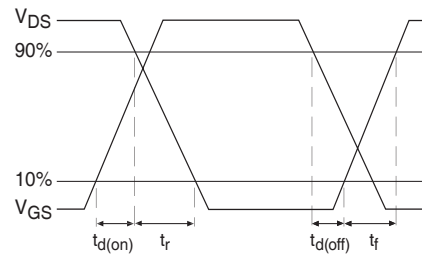


Fig 10b. Switching Time Waveforms

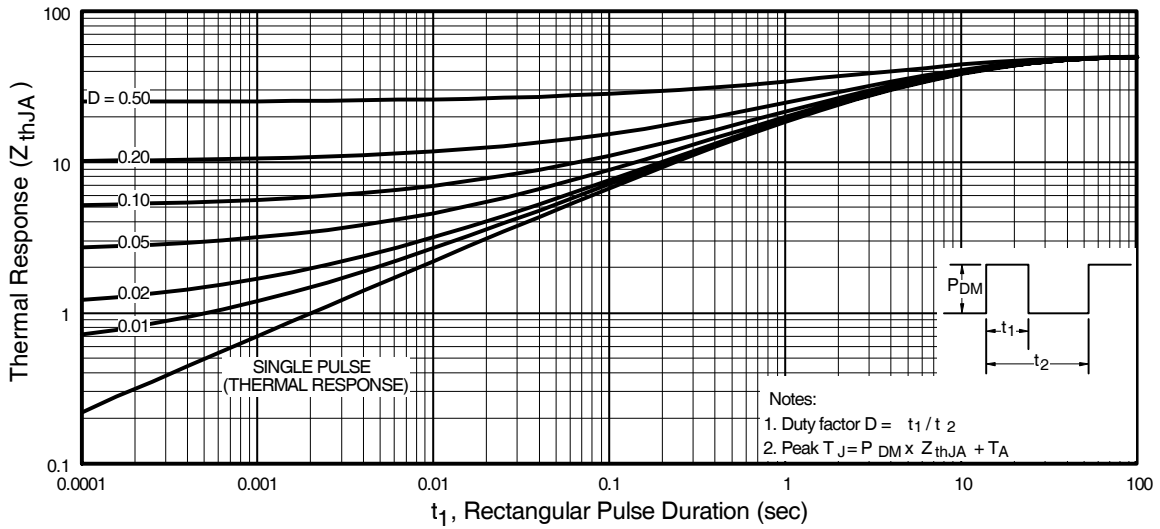


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

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International
IR Rectifier

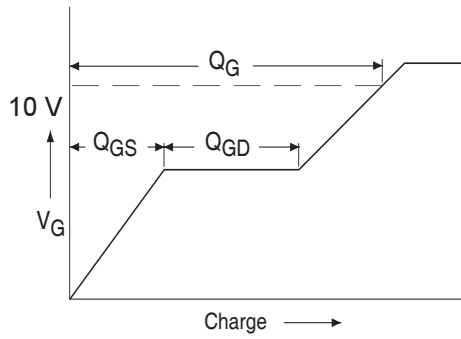


Fig 12a. Basic Gate Charge Waveform

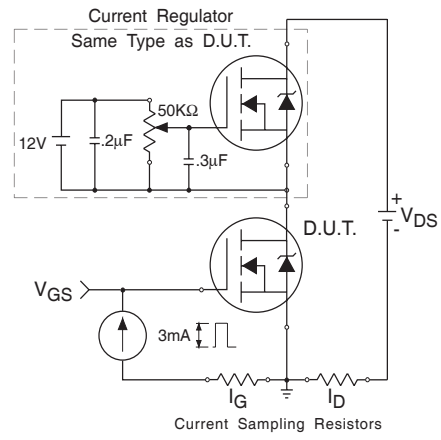
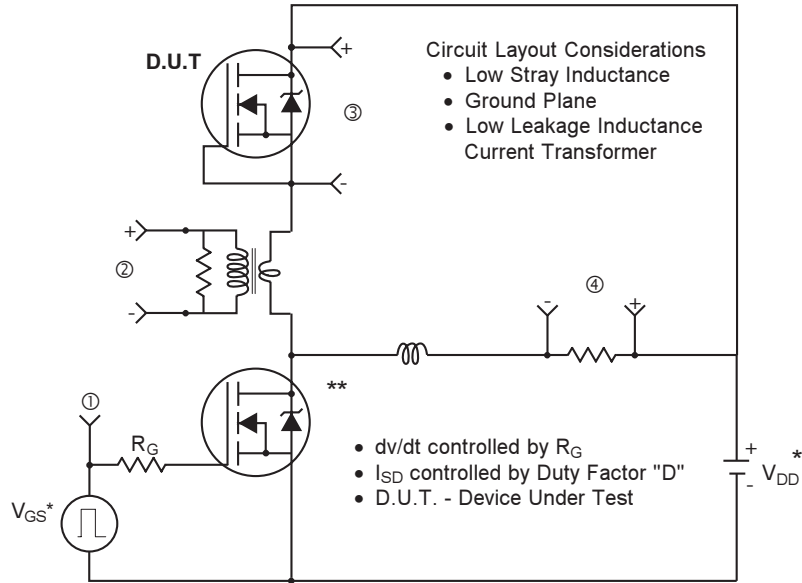


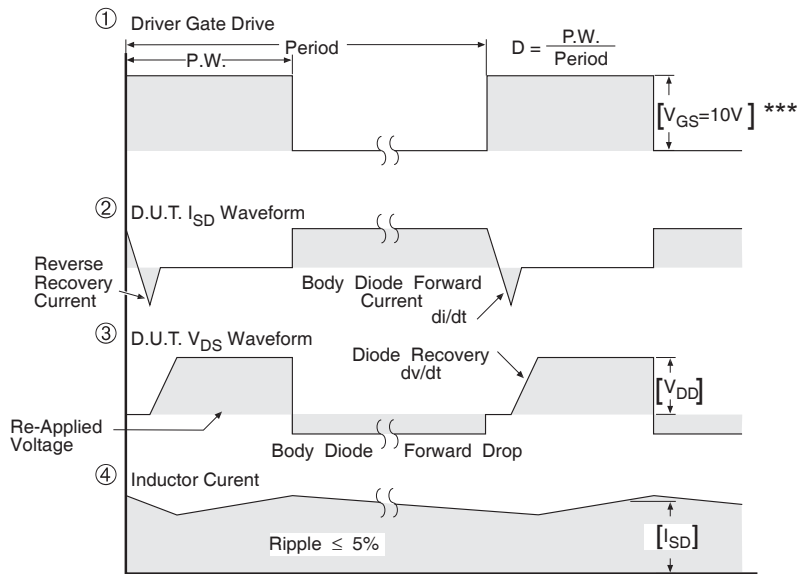
Fig 12b. Gate Charge Test Circuit

Peak Diode Recovery dv/dt Test Circuit



* Reverse Polarity for P-Channel

** Use P-Channel Driver for P-Channel Measurements



*** $V_{GS} = 5.0V$ for Logic Level and 3V Drive Devices

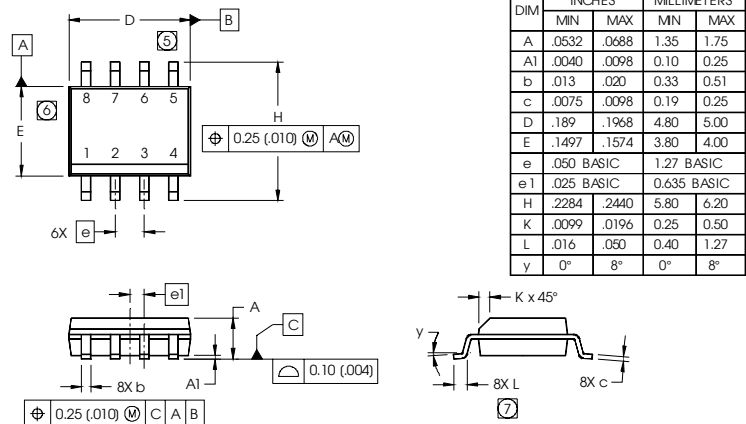
Fig 13. For N-Channel HEXFETS

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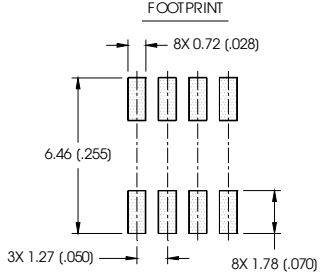


SO-8 Package Outline

Dimensions are shown in millimeters (inches)

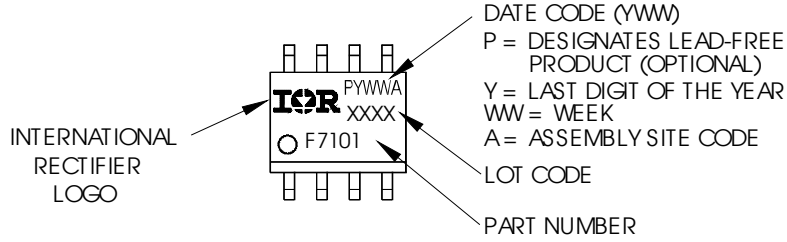


- NOTES:
1. DIMENSIONING & TOLERANCING PER ASME Y14.5M-1994.
 2. CONTROLLING DIMENSION: MILLIMETER
 3. DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).
 4. OUTLINE CONFORMS TO JEDEC OUTLINE MS-012AA.
 5. DIMENSION DOES NOT INCLUDE MOLD PROTRUSIONS. MOLD PROTRUSIONS NOT TO EXCEED 0.15 (.006).
 6. DIMENSION DOES NOT INCLUDE MOLD PROTRUSIONS. MOLD PROTRUSIONS NOT TO EXCEED 0.25 (.010).
 7. DIMENSION IS THE LENGTH OF LEAD FOR SOLDERING TO A SUBSTRATE.



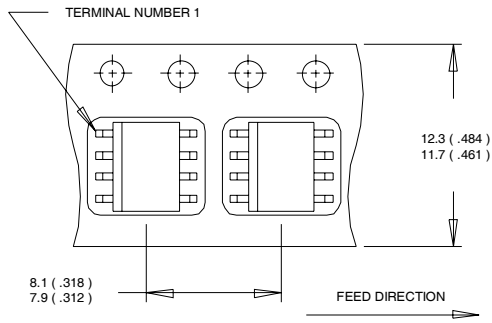
SO-8 Part Marking Information (Lead-Free)

EXAMPLE: THIS IS AN IRF7101 (MOSFET)



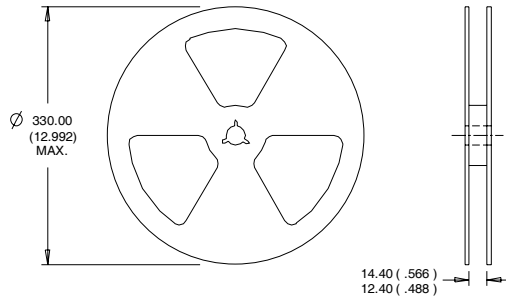
SO-8 Tape and Reel

Dimensions are shown in millimeters (inches)



NOTES:

1. CONTROLLING DIMENSION : MILLIMETER.
2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS(INCHES).
3. OUTLINE CONFORMS TO EIA-481 & EIA-541.



NOTES :

1. CONTROLLING DIMENSION : MILLIMETER.
2. OUTLINE CONFORMS TO EIA-481 & EIA-541.

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 Qualifications Standards can be found on IR's Web site.

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